

Product/Process Change Notification

N° 2023-114-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Introduction of an additional assembly production and final test location at Infineon Technologies (Wuxi) Co. Ltd., Wuxi, China for products IPGx

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2024-06-06.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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[Chairman of the Supervisory Board](#) Dr. Herbert Diess

[Management Board](#) Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

[Registered office](#) Neubiberg [Commercial register](#) Amtsgericht München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2023-114-A_[customer-no].pdf

Detailed change information

Subject: Introduction of an additional assembly production and final test location at Infineon Technologies (Wuxi) Co. Ltd., Wuxi, China for products IPGx

Reason/Motivation: Due to increasing demand for Infineon Automotive products exceeding current capacity in Melaka, Infineon is extending manufacturing capabilities to Wuxi and enabling flexible production for TDSON Duo packages.

Description	Old	New
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	CEL1772 HF9-SS	CEL1772 HF9-SS AND CEL9240HF40M3
PROCESS - ASSEMBLY: Move of all or part of assembly to a different location/site/subcontractor	Infineon Technologies (Malaysia) Sdn. Bhd.	Infineon Technologies (Malaysia) Sdn. Bhd. AND Infineon Technologies (Wuxi) Co. Ltd.
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	Infineon Technologies (Malaysia) Sdn. Bhd.	Infineon Technologies (Malaysia) Sdn. Bhd. AND Infineon Technologies (Wuxi) Co. Ltd.

Product identification

Traceability assured via date code.
No change in SP ordering number.

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Anticipated impact of change

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.

DeQuMa-ID(s): SEM-PA-11 / SEM-PA-18 / SEM-TF-01

Attachments

PCN_2023-114-A_[customer-no].pdf	affected product list
2_cip23114_A	qualification report, available upon request
3_cip23114_A	customer information package, available upon request

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2024-10-26
Last order date (LOD) [2]	2024-10-26
Last delivery date (LDD) [3]	2025-04-26

[1] Provided date or earlier after customer approval.

[2] Last date where orders for unchanged products will be accepted.

[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.